

Prashant K Kulshreshtha

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3189202/publications.pdf>

Version: 2024-02-01

17
papers

194
citations

1478505

6
h-index

1058476

14
g-index

18
all docs

18
docs citations

18
times ranked

343
citing authors

#	ARTICLE	IF	CITATIONS
1	Direct observation of mineral-organic composite formation reveals occlusion mechanism. Nature Communications, 2016, 7, 10187.	12.8	110
2	Nano-indentation: A tool to investigate crack propagation related phase transitions in PV silicon. Solar Energy Materials and Solar Cells, 2012, 96, 166-172.	6.2	26
3	Harnessing entropic and enthalpic contributions to create a negative tone chemically amplified molecular resist for high-resolution lithography. Nanotechnology, 2014, 25, 315301.	2.6	10
4	Silicon PV Wafers: Mechanical Strength and Correlations with Defects and Stress. Solid State Phenomena, 2011, 178-179, 79-87.	0.3	7
5	Oxygen Precipitation Related Stress-Modified Crack Propagation in High Growth Rate Czochralski Silicon Wafers. Journal of the Electrochemical Society, 2011, 159, H125-H129.	2.9	7
6	The effects of different types of additives on growth of biomineral phases investigated by in situ atomic force microscopy. Journal of Crystal Growth, 2019, 509, 8-16.	1.5	7
7	Effect of nickel contamination on high carrier lifetime n-type crystalline silicon. Journal of Applied Physics, 2012, 111, 033702.	2.5	6
8	Mechanistic Pathways for the Molecular Step Growth of Calcium Oxalate Monohydrate Crystal Revealed by In Situ Liquid-Phase Atomic Force Microscopy. ACS Applied Materials & Interfaces, 2021, 13, 37873-37882.	8.0	5
9	Selective Laser Ablation in Resists and Block Copolymers for High Resolution Lithographic Patterning. Journal of Photopolymer Science and Technology = [Fotopolimer Konwakai Shi], 2015, 28, 663-668.	0.3	4
10	Nanoscale modulus and surface chemistry characterization for collapse free resists. Proceedings of SPIE, 2013, , .	0.8	3
11	Sub-20nm lithography negative tone chemically amplified resists using cross-linker additives. Proceedings of SPIE, 2013, , .	0.8	3
12	Crack Propagation in Large Diameter PV Silicon. ECS Transactions, 2010, 33, 25-32.	0.5	2
13	Characterization of film materials in wafer processing technology development by XPS. Journal of Electron Spectroscopy and Related Phenomena, 2019, 231, 57-67.	1.7	2
14	Amorphization during Fracture of Thin Photovoltaic Silicon Wafers. ECS Transactions, 2010, 25, 49-55.	0.5	1
15	Revealing beam-induced chemistry using modulus mapping in negative-tone EUV/e-beam resists with and without cross-linker additives. Proceedings of SPIE, 2015, , .	0.8	1
16	Evaluating Amorphization Around Micro-Cracks in PV Silicon. Materials Research Society Symposia Proceedings, 2009, 1210, 1.	0.1	0
17	In-Situ Electrical Measurements of Thin Photovoltaic Silicon Wafers during Nanoindentation. ECS Transactions, 2010, 25, 41-48.	0.5	0